Product / Package Information

Package	TQFP_EP
Body Size (mm)	14 X 14 X 1.0 (5.0 EP)
Lead Count	100
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A and B

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica fused	60676-86-0	2.98E-01	88	880000	59.89	598851
Thermosets	Epoxy & Phenol resin	Proprietary	3.89E-02	11.5	115000	7.83	78259
Other inorganic materials	Carbon black	1333-86-4	1.69E-03	0.5	5000	0.34	3403
Subtotal			3.38 E-01	100.00	1000000	68.05	680513

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.27E-01	99.25	992500	25.58	255761
Copper & its alloys	Chromium	7440-47-3	3.85E-04	0.30	3000	0.08	773
Copper & its alloys	Tin	7440-31-5	3.20E-04	0.25	2500	0.06	644
Copper & its alloys	Zinc	7440-66-6	2.56E-04	0.20	2000	0.05	515
Subtotal			1.28 E-01	100.00	1000000	25.77	257694

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	8.00 E-04	100.0	1000000	0.16	1608

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.54 E-03	100.0	1000000	1.52	15165

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	2.10 E-03	100.00	1000000	0.42	4224

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.64 E-02	100.0	1000000	3.30	33016

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Silver	7440-22-4	2.80E-03	72.40	724000	0.56	5633
Thermoset	Epoxy compound	Proprietary	7.00E-04	18.10	181000	0.14	1408
Other organic materials	Anhydrides	Proprietary	2.63E-04	6.79	67900	0.05	528
Other organic materials	Polymeric material	Proprietary	1.05E-04	2.71	27100	0.02	211
Subtotal	Subtotal		3.87 E-03	100.00	1000000	0.78	7781

	Weight (g)	Percentage (%)	PPM
Package Totals	**4.97 E-01**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary